



1755

In re Patent Application of: )  
**SMYTH ET AL.** )  
 )  
Serial No. **10/022,595** )  
 )  
Confirmation No. **5966** )  
 )  
Filing Date: **DECEMBER 13, 2001** )  
 )  
For: **ELECTRONIC MODULE INCLUDING A** )  
**LOW TEMPERATURE CO-FIRED** )  
**CERAMIC (LTCC) SUBSTRATE WITH** )  
**A CAPACITIVE STRUCTURE EMBEDDED** )  
**THEREIN AND RELATED METHODS** )

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TRANSMITTAL OF FORMAL DRAWINGS

Director, U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

Enclosed are four (4) sheets of formal drawings to be  
filed in the above-identified patent application.

Respectfully submitted,

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